

# SPECIFICATIONS AGM 1601F-401

### **SPECIFICATION**

CUSTOMER :		
MODULE NO.:	AGM 1601	F-401
APPROVED BY:		
( FOR CUSTOMER USE ONLY )	PCB VERSION:	DATA:

CHECKED BY	PREPARED BY

•	VERSION	DATE	REVISED PAGE NO.	SUMMARY
	F	2018/06/21		Modify PCB.



MODLE NO:

#### **RECORDS OF REVISION**

#### DOC. FIRST ISSUE

VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2006/08/23		First issue
A	2008/09/12		Modify Character
			Generator ROM Pattern
В	2011/10/21		Correct ST7066IC
			information.
С	2015/01/20		Remove IC information
D	2015/07/03		Modify FR->PCB=4.8mm.
Е	2016/01/27		Modify Precautions in use
			of LCD Modules
			& Static electricity test
F	2018/06/21		Modify PCB.

## **Contents**

- 1. Precautions in use of LCD Modules
- 2.General Specification
- 3. Absolute Maximum Ratings
- 4. Electrical Characteristics
- 5. Optical Characteristics
- 6.Interface Pin Function
- 7. Contour Drawing & Block Diagram
- 8. Character Generator ROM Pattern
- 9.Reliability
- 11. Inspection specification
  - 12. Material List of Components for RoHs
  - 13.Recommendable Storage

## 1.Precautions in use of LCD Modules

(1) Avoid applying excessive shocks to the module or making any alterations or modifications to it. (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of

LCD module.

- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) AGTechnologies have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) AGTechnologies have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, AGTechnologies have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

## **2.General Specification**

Item	Dimension	Unit			
Number of Characters	16 characters x 1Lines	_			
Module dimension	80.0 x 36.0 x 9.7 (MAX)	mm			
View area	66.0 x 16.0	mm			
Active area	59.62 x 6.56	mm			
Dot size 0.55 x 0.75		mm			
Dot pitch	0.63 x 0.83				
Character size	3.07 x 6.56	mm			
Character pitch	3.77 x 6.56	mm			
LCD type	STN Positive, Yellow Green Reflective  (In LCD production, It will occur slightly color difference. We can only guarantee the same color in the same batch.)				
Duty	1/16				
View direction	6 o'clock				
Backlight Type	Without backlight				
IC	ST7066U				

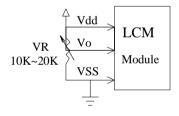
## **3.Absolute Maximum Ratings**

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	$T_{\mathrm{OP}}$	-20	_	+70	$^{\circ}\! \mathbb{C}$
Storage Temperature	$T_{ST}$	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	V <sub>I</sub>	$V_{SS}$	_	$V_{\mathrm{DD}}$	V
Supply Voltage For Logic	$V_{ m DD} ext{-}V_{ m SS}$	-0.3	_	7	V
Supply Voltage For LCD	$V_{DD}$ - $V_{o}$	-0.3	_	13	V

## **4.Electrical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$	_	4.5	5.0	5.5	V
Supply Voltage For LCD		Ta=-20°C	_	_	5.6	V
*Note	$V_{DD}$ - $V_0$	Ta=25°C	4.2	4.35	4.5	V
		Ta=70°C	3.7	_	_	V
Input High Volt.	$V_{\mathrm{IH}}$	_	0.7 V <sub>DD</sub>	_	$V_{\mathrm{DD}}$	V
Input Low Volt.	$V_{\rm IL}$	_	Vss	_	0.6	V
Output High Volt.	$V_{\mathrm{OH}}$	_	3.9	_	$V_{\mathrm{DD}}$	V
Output Low Volt.	V <sub>OL</sub>	_	0	_	0.4	V
Supply Current	$I_{\mathrm{DD}}$	V <sub>DD</sub> =5.0V	1.0	1.2	1.5	mA

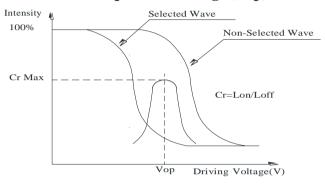
<sup>\*</sup> Note: Please design the VOP adjustment circuit on customer's main board



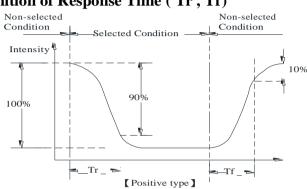
## **5.Optical Characteristics**

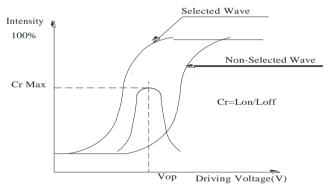
Item	Symbol	Condition	Min	Тур	Max	Unit
X7. A 1	θ	CR≧2	0	_	20	$\Psi = 180^{\circ}$
	θ	CR≧2	0	_	40	$\Psi = 0^{\circ}$
View Angle	θ	CR≧2	0	_	30	$\Psi = 90^{\circ}$
	θ	CR≧2	0	_	30	$\psi = 270^{\circ}$
Contrast Ratio	CR	_	_	3	_	_
D	T rise	_	_	150	200	ms
Response Time	T fall	_	_	150	200	ms

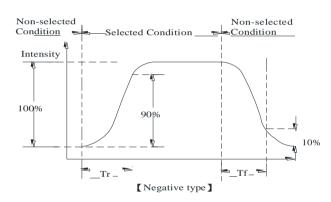
#### **Definition of Operation Voltage (Vop)**



#### Definition of Response Time ( Tr, Tf)



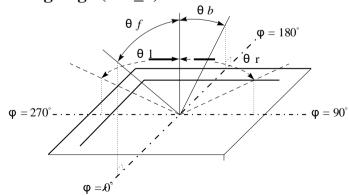




#### **Conditions:**

Operating Voltage: Vop Frame Frequency: 64 HZ Viewing Angle( $\theta$ ,  $\phi$ ):  $0^{\circ}$ ,  $0^{\circ}$ Driving Waveform: 1/N duty, 1/a bias

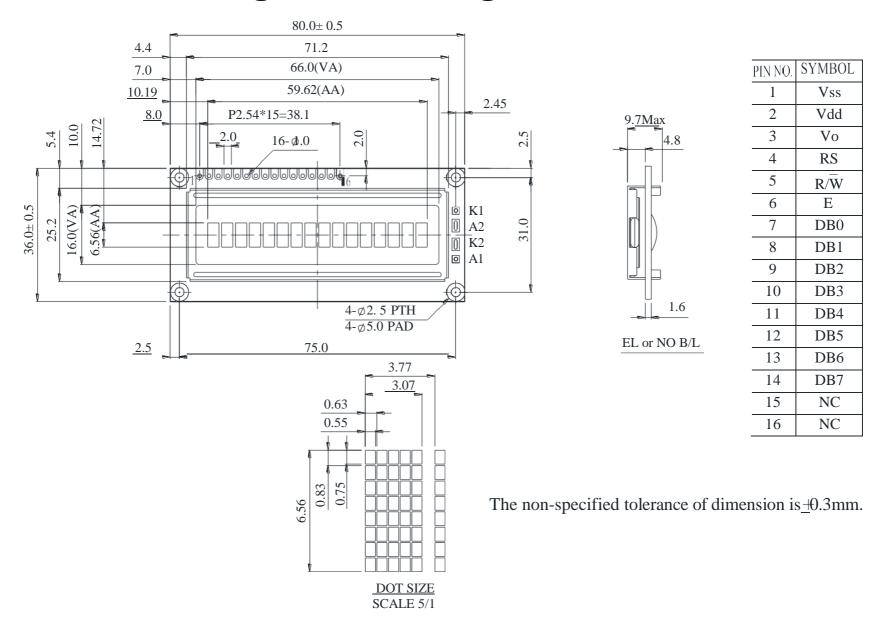
Definition of viewing angle(CR≥2)

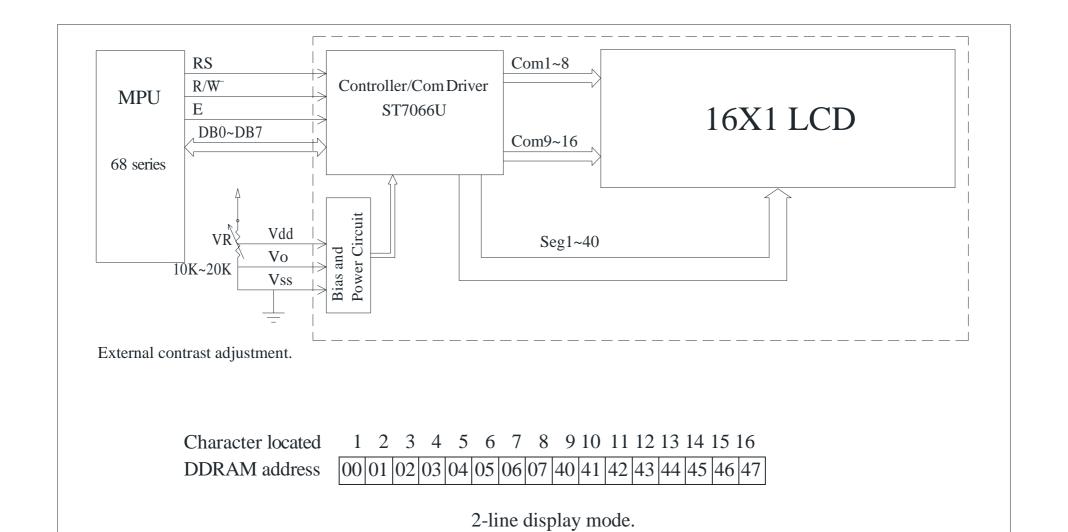


## **6.Interface Pin Function**

Pin No.	Symbol	Level	Description
1	$V_{SS}$	0V	Ground
2	$V_{\mathrm{DD}}$	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read L: Write
6	Е	H,H→L	Chip enable signal
7	DB0	H/L	Data bit 0
8	DB1	H/L	Data bit 1
9	DB2	H/L	Data bit 2
10	DB3	H/L	Data bit 3
11	DB4	H/L	Data bit 4
12	DB5	H/L	Data bit 5
13	DB6	H/L	Data bit 6
14	DB7	H/L	Data bit 7
15	NC	_	No connection
16	NC		No connection

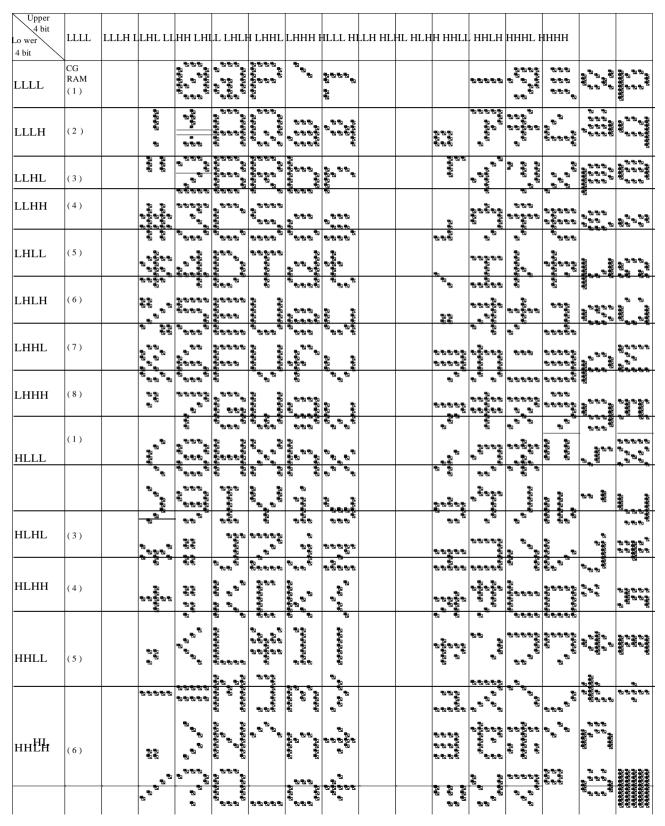
## 7. Contour Drawing & Block Diagram





## 8. Character Generator ROM Pattern

Table.2



## 9. Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

	Environmental Test						
Test Item	Content of Test	Test Condition	Not e				
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2				
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2				
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	_				
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1				
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90% RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2				
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles					
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3				
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times					

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

## 10.Inspection specification

NO	Item	Criterion				AQL
01	Electrical Testing	Missing vertical, horizontal segment, segment contrast defect.  Missing character, dot or icon.  Display malfunction.  No function or no display.  Current consumption exceeds product specifications.  LCD viewing angle defect.  Mixed product types.  Contrast defect.				
02	Black or white spots on LCD (display only)	three white or b	2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.  2.2 Densely spaced: No more than two spots or lines within 3mm			
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type $\Phi=(x+y)/2$ X  3.2 Line type : (	¥ ▼Y	SIZE $ \Phi \le 0.10 $ $ 0.10 < \Phi \le 0.20 $ $ 0.20 < \Phi \le 0.25 $ $ 0.25 < \Phi $	Acceptable Q TY Accept no dense  2 1 0  Acceptable Q TY Acceptable Q TY Accept no dense  2 As round type	2.5
04	Polarizer bubbles	If bubbles are v judge using blace specifications, re- to find, must che specify direction	ck spot not easy eck in	Size $\Phi$ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5

NO	Item	Criterion			AQL		
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination					
		Symbols Define:					
		x: Chip length y: Ch	nip width z: Ch	ip thickness			
		k: Seal width t: Gla	ass thickness a: LC	D side length			
		L: Electrode pad length:					
		6.1 General glass chip:					
		6.1.1 Chip on panel surface	e and crack between	panels:			
		z: Chip thickness y:	Chip width	x: Chip length			
		$Z \le 1/2t$ No	ot over viewing	x ≤ 1/8a			
06	Chipped	ar	ea		2.5		
	glass	$1/2t < z \le 2t$ No	ot exceed 1/3k	x ≤ 1/8a			
		○ If there are 2 or more choose 6.1.2 Corner crack: $ z: Chip thickness $ $ y: Z \le 1/2t $ No are	Chip width ot over viewing ea ot exceed 1/3k	of each chip. $x$ : Chip length $x \le 1/8a$ $x \le 1/8a$			

NO	Item	Criterion			AQL	
	Glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:				
06		$\begin{array}{ c c c c c }\hline y: Chip \ width & x: Chip \ length & z: Chip \ thickness \\\hline y \le 0.5mm & x \le 1/8a & 0 < z \le t \\\hline 6.2.2 \ Non-conductive \ portion: \\\hline \\ L & L \\\hline \end{array}$				
		y: Chip width	z y x: Chip length	z: Chip thickness		
		$y \le L$ $y \le L$ $y \le L$	$x \le 1/8a$ s the ITO terminal.	$0 < z \le t$		
		remain and be inspected according to electrode terminal specifications.  Of the product will be heat sealed by the customer, the alignment mark not be damaged.  6.2.3 Substrate protuberance and internal crack.				
		X	y: width	x: length		
			y≦1/3L	$x \leq a$		
		"				

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08		8.1 Illumination source flickers when lit.	
	Backlight	8.2 Spots or scratched that appear when lit must be judged.	
	elements	Using LCD spot, lines and contamination standards.	
		8.3 Backlight doesn't light or color wrong.	0.65
	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5
09		stains or other contamination.	
		9.2 Bezel must comply with job specifications.	0.65
		10.1 COB seal may not have pinholes larger than 0.2mm or	2.5
		contamination.	
		10.2 COB seal surface may not have pinholes through to the IC.	2.5
	PCB · COB	10.3 The height of the COB should not exceed the height	0.65
		indicated in the assembly diagram.	
		10.4 There may not be more than 2mm of sealant outside the	2.5
		seal area on the PCB. And there should be no more than three	
		places.	
		10.5 No oxidation or contamination PCB terminals.	2.5
10		10.6 Parts on PCB must be the same as on the production	0.65
10		characteristic chart. There should be no wrong parts, missing	
		parts or excess parts.	
		10.7 The jumper on the PCB should conform to the product	0.65
		characteristic chart.	
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	2.5
		screw hold pad, make sure it is smoothed down.	
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5
		X	
		$X * Y \le 2mm^2$	
11	Soldering	11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections,	2.5
		oxidation or icicle.	
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface	2.5
		Pin (OLB) of TCP.	
		122 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		124 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
		pin must be present or look as if it cause the interface pin to sever.	
	General	12.6 The residual rosin or tin oil of soldering (component or chip	2.5
12		component) is not burned into brown or black color.	
	appearance	127 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	0.65
		specification sheet.	
		12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65

## 11. Material List of Components for RoHs

1. AGTECHNOLOGIES, Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2. Process for RoHS requirement : (only for RoHS inspection)

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow:  $250^{\circ}$ C, 30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. :  $235\pm5$ °C;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

## 13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

#### AGTechnologies <u>LCM Sample Estimate Feedback Sheet</u>

Module Number .			Page: 1
1 · Panel Specification:			
1. Panel Type:	Pass	□ NG ,	
2. View Direction:	Pass	□ NG ,	
3. Numbers of Dots:	Pass	□ NG ,	
4. View Area:	Pass	□ NG ,	
5. Active Area:	Pass	☐ NG,	
6. Operating Temperature:	Pass	☐ NG,	
7. Storage Temperature:	Pass	☐ NG,	
8. Others:	_		
2 · Mechanical Specification :			
1. PCB Size:	Pass	□ NG ,	
2. Frame Size:	Pass	□ NG ,	
3. Materal of Frame:	Pass	□ NG ,	
4. Connector Position:	Pass	☐ NG ,	
5. Fix Hole Position:	Pass	□ NG,	
6. Backlight Position:	Pass	☐ NG ,	
7. Thickness of PCB:	Pass	☐ NG ,	
8. Height of Frame to PCB:	Pass	☐ NG ,	
9. Height of Module:	Pass	□ NG ,	
10. Others:	Pass	☐ NG ,	
3 · Relative Hole Size:			
1. Pitch of Connector:	Pass	☐ NG,	
2. Hole size of Connector:	Pass	☐ NG,	
3. Mounting Hole size:	Pass	☐ NG,	
4. Mounting Hole Type:	Pass	☐ NG,	
5. Others:	Pass	☐ NG,	
4 · <u>Backlight Specification</u> :			
1. B/L Type:	Pass	□ NG ,	
2. B/L Color:	Pass	☐ NG ,	
3. B/L Driving Voltage (Referen	ence for LED	Type): $\square$ Pass	□ NG ,
4. B/L Driving Current:	Pass	□ NG ,	
5. Brightness of B/L:	Pass	□ NG ,	
6. B/L Solder Method:	Pass	□ NG ,	
7. Others:	Pass	□ NG ,	
	> > Go to	page 2 < <	

AGTechnologies Module Number:	Page: 2		
5 · Electronic Characteristics of	f Module :		ruge. 2
1. Input Voltage:	Pass	$\square$ NG	
2. Supply Current:	Pass	$\square$ NG	
3. Driving Voltage for LCD:	Pass	$\square$ NG	
4. Contrast for LCD:	Pass	$\square$ NG	
5. B/L Driving Method:	Pass	$\square$ NG	
6. Negative Voltage Output:	Pass	$\square$ NG	
7. Interface Function:	Pass	$\square$ NG	
8. LCD Uniformity:	Pass	$\square$ NG	
9. ESD test:	Pass	$\square$ NG	
10. Others:	Pass	$\square$ NG	
6 · <u>Summary</u> :			
Sales signature:		_	

Customer Signature :

**Date**: / /